

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**DECLARATION FOR PATENT APPLICATION**

As the below named inventors, we hereby declare that:

Our residence, post office address and citizenship are as stated below next to our names.

We believe we are the original, first and joint inventors of the subject matter which is claimed and for which a patent is sought on the invention entitled

**METHOD OF FORMING A METAL SEED LAYER FOR  
SUBSEQUENT PLATING**

The specification of which is attached hereto.

We hereby state that we have reviewed and understand the contents of the above identified specification, including the claims, as amended by an amendment, if any, specifically referred to in this oath or declaration.

We acknowledge the duty to disclose all information known to me which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56.

We hereby claim foreign priority benefits under Title 35, United States Code, § 119/365 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

None

We hereby claim the benefit under Title 35, United States Code, § 120/365 of any United States and PCT international application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, we acknowledge the duty to disclose all information known to us to be material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56(a) which became available between the filing date of the prior application and the national or PCT international filing date of this application:

None

We hereby declare that all statements made herein of our own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001

of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Please address all correspondence to Thomas J. D'Amico of Dickstein Shapiro Morin & Oshinsky LLP located at 2101 L Street, NW, Washington, DC 20037-1526. Telephone calls should be made to Thomas J. D'Amico by dialing (202) 828-2232.

Full name of 1st joint inventor: Terry L. Gilton

Inventor's signature

Date

4/1/99

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Full name of 2nd joint inventor: Dinesh Chopra

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Date

4/1/99

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PATENT  
Docket No.: M4065.135/P135  
Micron No.: 98-0673.00/US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Patent Application  
Inventor: Terry L. GILTON et al.

Serial No.: Not Yet Assigned      Group Art Unit:      Not Yet Assigned

Filed: Concurrently Herewith      Examiner: Not Yet Assigned

For: METHOD OF FORMING A  
METAL SEED LAYER FOR  
SUBSEQUENT PLATING

POWER OF ATTORNEY BY ASSIGNEE AND  
CERTIFICATE BY ASSIGNEE UNDER 37 CFR § 3.73(b)

Micron Technology, Inc., assignee of the entire right, title and interest in the above-identified application by virtue of the assignment attached hereto (which is also being submitted concurrently for recordation), hereby appoints the attorneys and agents of the firm of Dickstein Shapiro Morin & Oshinsky LLP located at 2101 L Street, NW, Washington, DC 20037-1526, listed as follows: Gary M. Hoffman, 26,411; Thomas J. D'Amico, 28,371; Donald A. Gregory, 28,954; James W. Brady, Jr., 32,115; Jon D. Grossman, 32,699; Mark J. Thronson, 33,082; Laurence D. Fisher, 37,131; John R. Fuisz, 37,327; James M. Heintz, 41,828; June Cohan Lazar, P43,741; Brian A. Lemm, P43,748; Gianni Minutoli, 41,198; Eric Oliver, 35,307; William E. Powell, III, 39,803; James M. Silbermann, 40,413; and Richard Veltman, 36,957; and also attorneys Michael L. Lynch, 30,871; Lia M. Pappas, 34,095; W. Eric Webostad, 35,406; and Charles B. Brantley, II, 38,086 of

Micron Technology, Inc. as its attorneys with full power of substitution to prosecute this application and to transact all business in the Patent and Trademark Office in connection therewith.

The assignee certifies that the above-identified assignment has been reviewed and to the best of the assignee's knowledge and belief, title is in the assignee.

Please direct all correspondence regarding this application to the following:

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Dated: 4-1-99